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# TLE4961-1L

High Precision Automotive Hall Effect Latch

## Data Sheet

Revision 1.0, 2012-07-18

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**Revision History**

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<b>Revision 1.0, 2012-07-18</b>	
Document	Layout changes; Data sheets for PG-SC59-3-5 and PG-SOT23-3-15 seperated; Changes compared to last commen target data sheet revision 0.5
7	Overview changed
13	Storage temperature added; Table 3-1 Lifetime statement added
13,14	V <sub>Q</sub> Min changed
15	Table 3-5, Hysteresis changed
19-25	Graphs added

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# 1 Product Description



## 1.1 Overview

Characteristic	Supply Voltage	Supply Current	Sensitivity	Interface	Temperature
Bipolar Hall Effect Latch	3.0~32 V	1.6 mA	High B <sub>OP</sub> :2 mT B <sub>RP</sub> :-2 mT	Open Drain Output	-40°C to 170°C

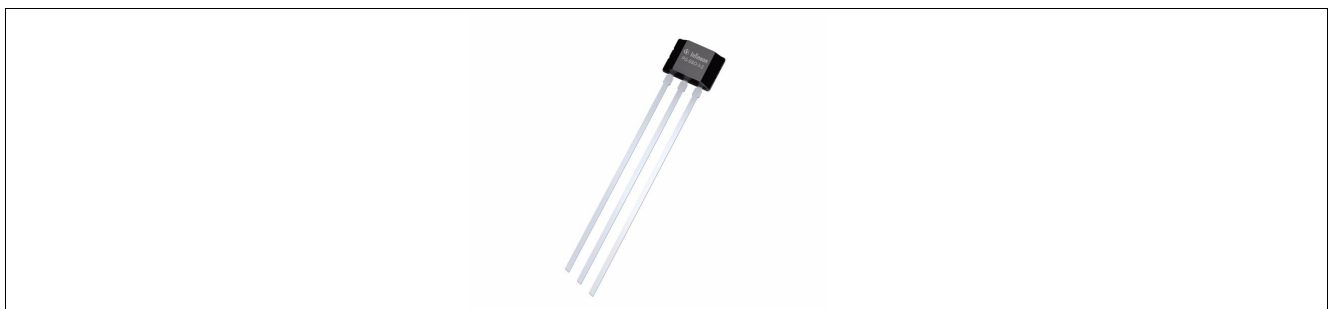


Figure 1-1 Image of TLE4961-1L in the PG-SSO-3-2 Package

## 1.2 Features

- 3.0 V to 32 V operating supply voltage
- Operation from unregulated power supply
- Reverse polarity protection (-18 V)
- Overvoltage capability up to 42 V without external resistor
- Output overcurrent & overtemperature protection
- Active error compensation
- High stability of magnetic thresholds
- Low jitter (typ. 0.35 μs)
- High ESD performance
- Leaded package PG-SSO-3-2 (TLE4961-1L)

## 1.3 Target Applications

Target applications for the TLE496x Hall switch family are all applications which require a high precision Hall switch with an operating temperature range from -40°C to 170°C. Its superior supply voltage range from 3.0 V to 32 V with overvoltage capability (e.g. load-dump) up to 42 V without external resistor makes it ideally suited for automotive and industrial applications.

The magnetic behavior as a latch and switching thresholds of typical ±2 mT make the device especially suited for the use with a pole wheel for index counting applications as e.g. power closing and window lifter.

Table 1-1 Ordering Information

Product Name	Product Type	Ordering Code	Package
TLE4961-1L	Hall Latch	SP000848038	PG-SSO-3-2



## 2 Functional Description

### 2.1 General

The TLE4961-1L is an integrated Hall effect latch designed specifically for highly accurate applications with superior supply voltage capability, operating temperature range and temperature stability of the magnetic thresholds.

### 2.2 Pin Configuration (top view)

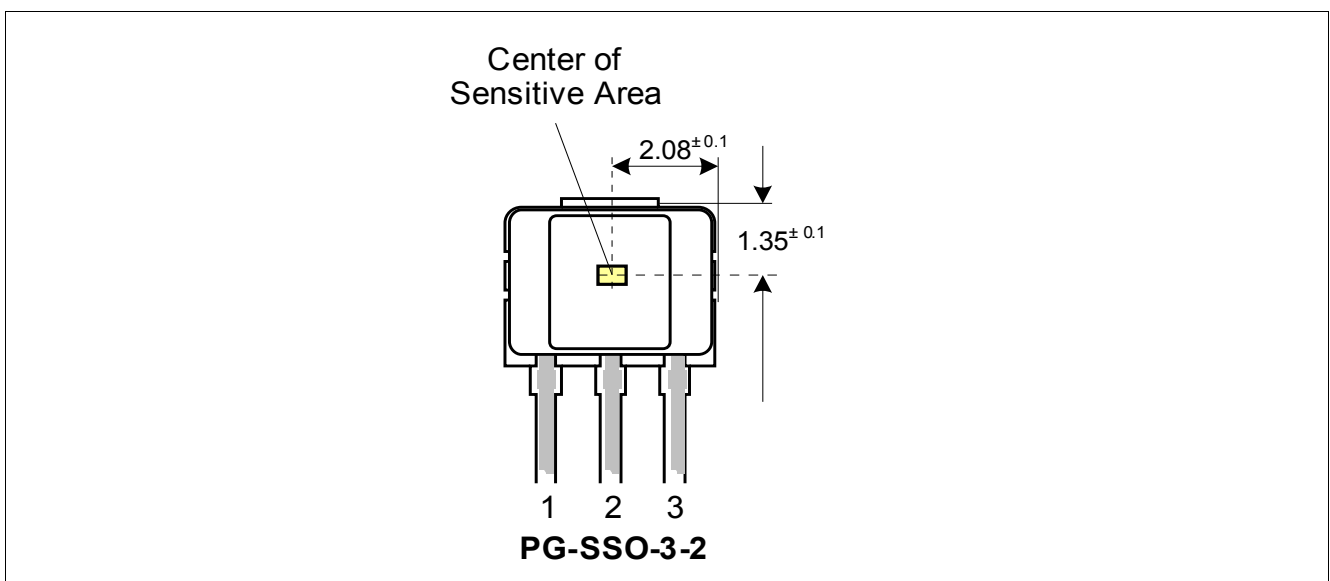


Figure 2-1 Pin Configuration and Center of Sensitive Area

### 2.3 Pin Description

Table 2-1 Pin Description PG-SSO-3-2

Pin No.	Symbol	Function
1	VDD	Supply voltage
2	GND	Ground
3	Q	Output

## 2.4 Block Diagram

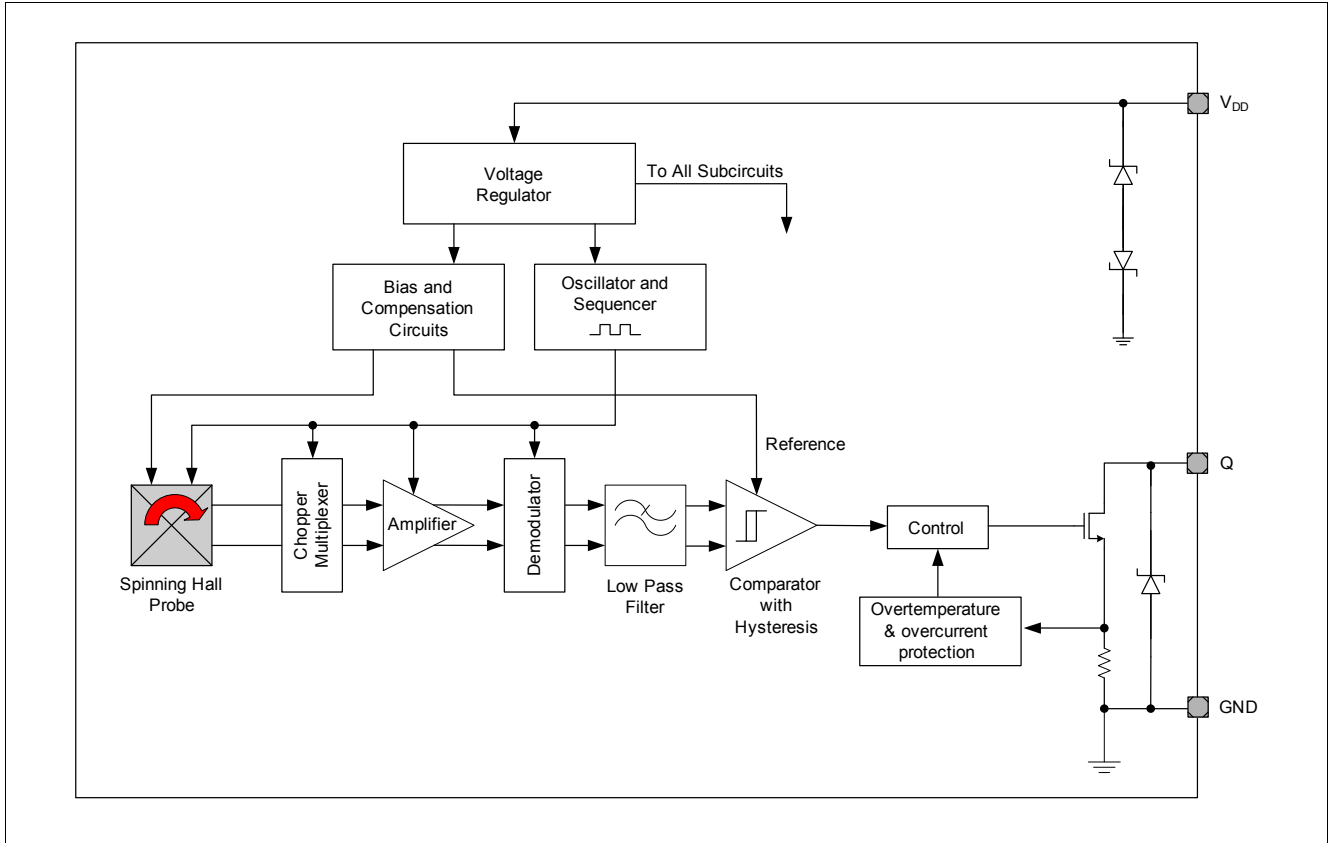


Figure 2-2 Functional Block Diagram TLE4961-1L

## 2.5 Functional Block Description

The chopped Hall IC switch comprises a Hall probe, bias generator, compensation circuits, oscillator and output transistor.

The bias generator provides currents for the Hall probe and the active circuits. Compensation circuits stabilize the temperature behavior and reduce influence of technology variations.

The active error compensation (chopping technique) rejects offsets in the signal path and the influence of mechanical stress to the Hall probe caused by molding and soldering processes and other thermal stress in the package. The chopped measurement principle together with the threshold generator and the comparator ensures highly accurate and temperature stable magnetic thresholds.

The output transistor has an integrated overcurrent and overtemperature protection.

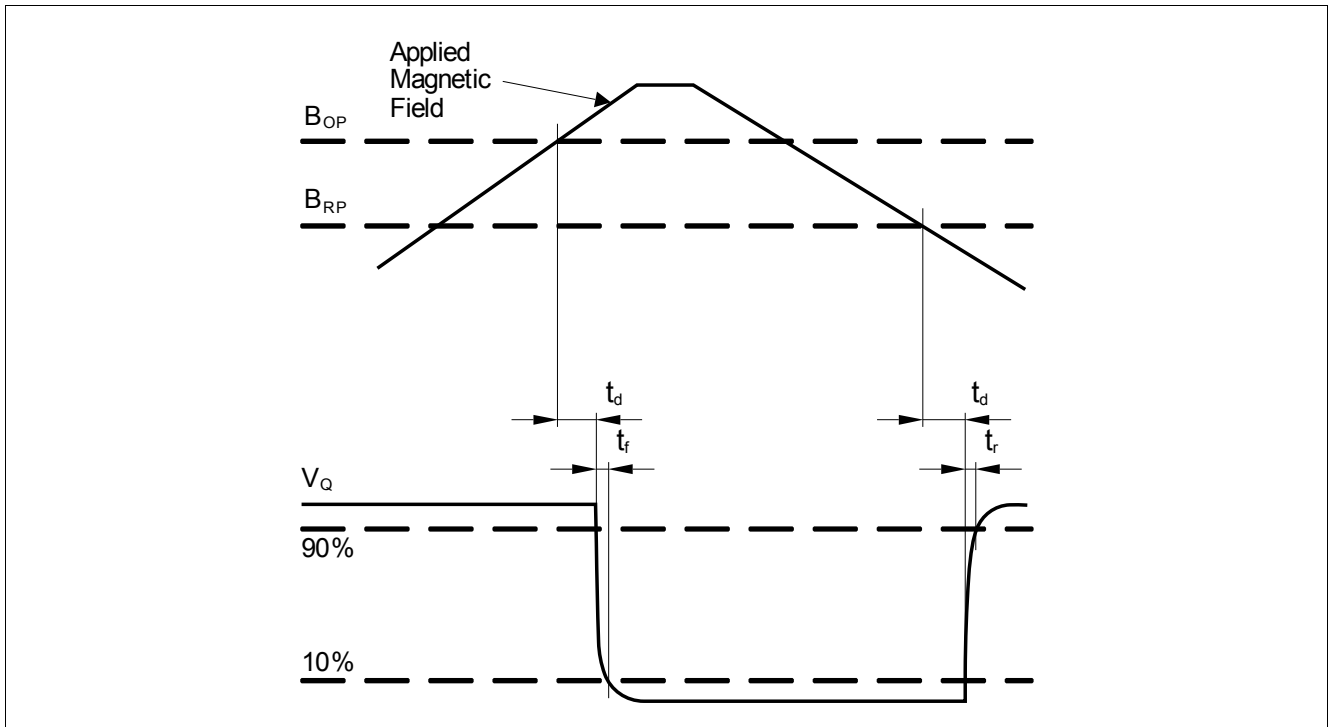


Figure 2-3 Timing Diagram TLE4961-1L

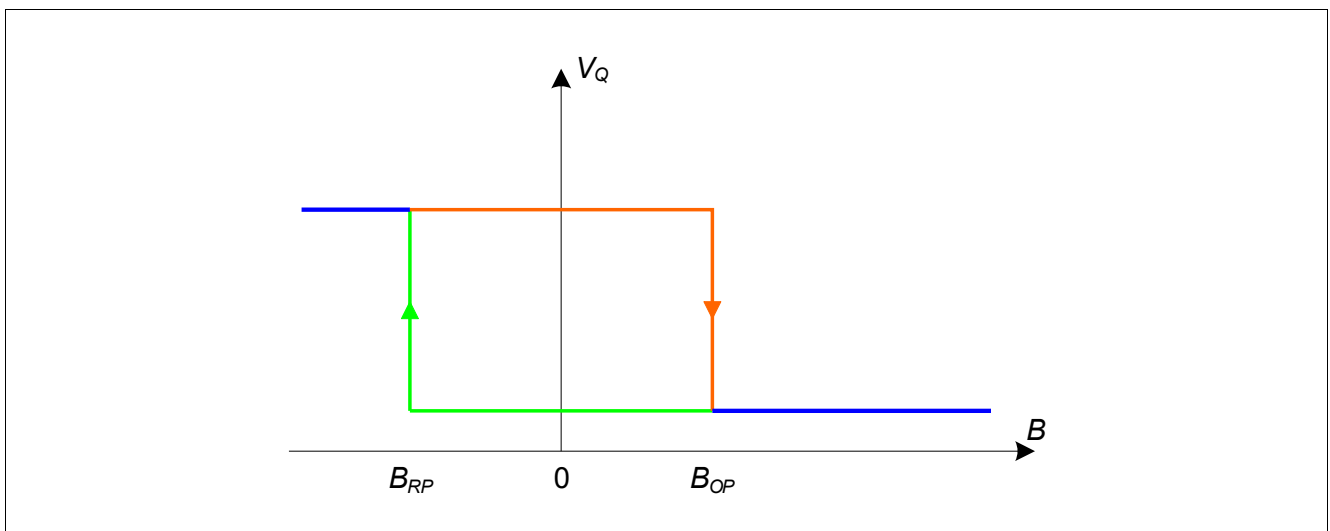


Figure 2-4 Output Signal TLE4961-1L

### 2.6 Default Start-up Behavior

The magnetic thresholds exhibit a hysteresis  $B_{HYS} = B_{OP} - B_{RP}$ . In case of a power-on with a magnetic field  $B$  within hysteresis ( $B_{OP} > B > B_{RP}$ ) the output of the sensor is set to the pull up voltage level ( $V_Q$ ) per default. After the first crossing of  $B_{OP}$  or  $B_{RP}$  of the magnetic field the internal decision logic is set to the corresponding magnetic input value.

$V_{DDA}$  is the internal supply voltage which is following the external supply voltage  $V_{DD}$ .

This means for  $B > B_{OP}$  the output is switching, for  $B < B_{RP}$  and  $B_{OP} > B > B_{RP}$  the output stays at  $V_Q$ .

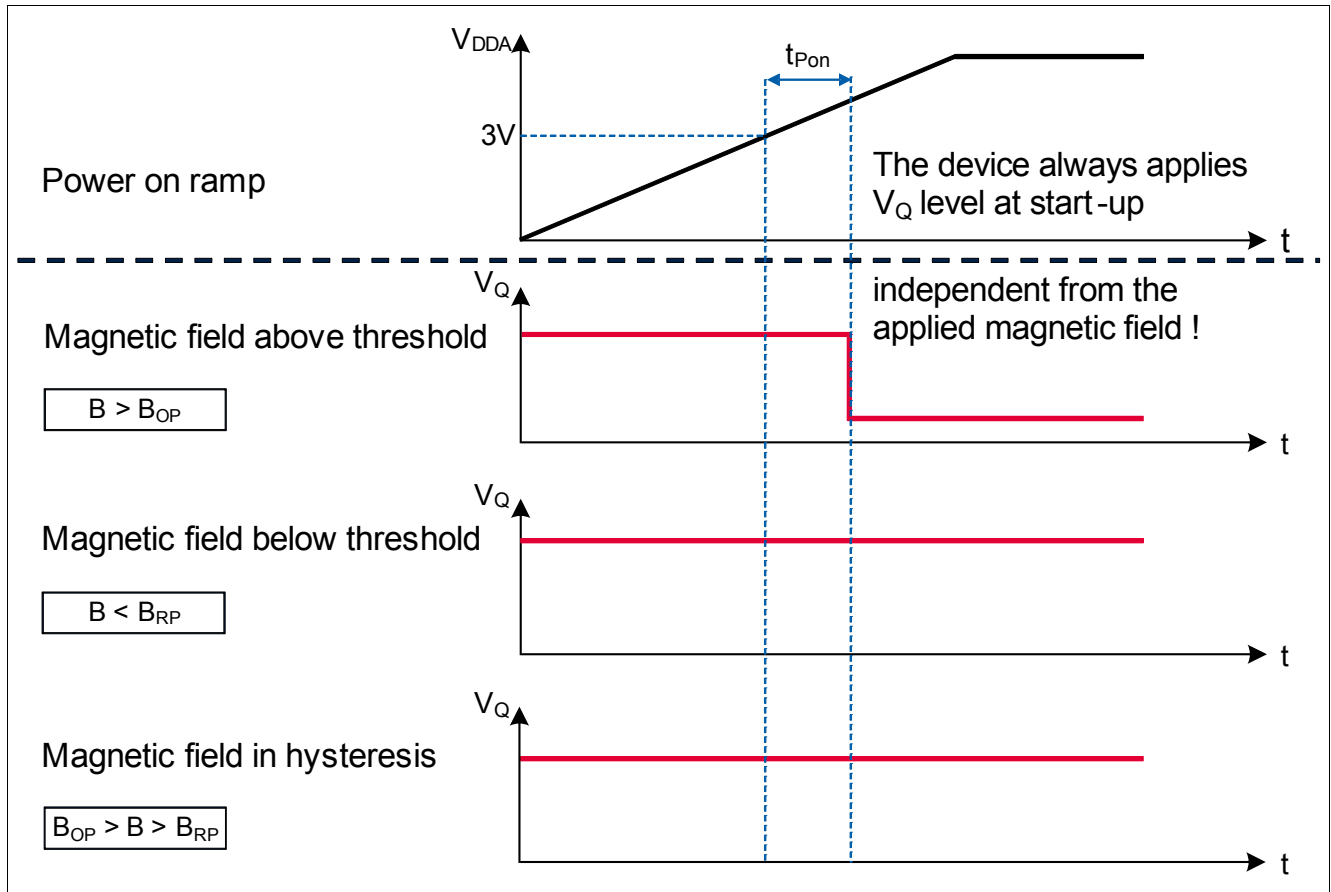


Figure 2-5 Illustration of the Start-up Behavior of the TLE4961-1L



### 3 Specification

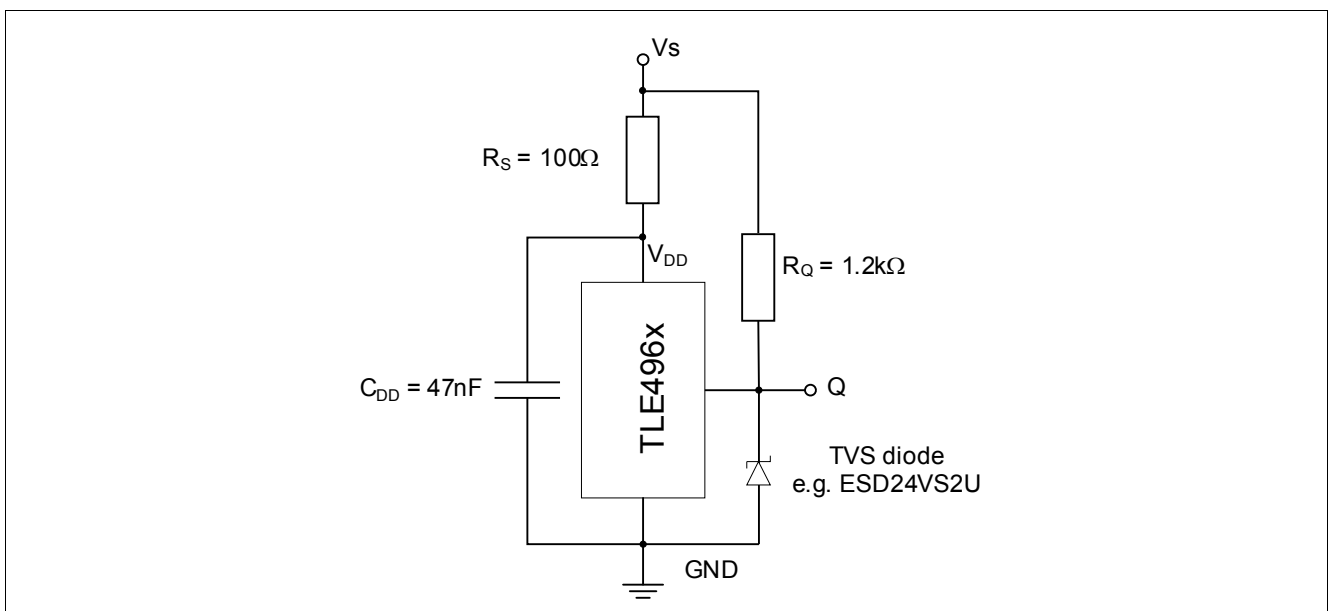
#### 3.1 Application Circuit

The following **Figure 3-1** shows one option of an application circuit. As explained above the resistor  $R_S$  can be left out (see **Figure 3-2**). The resistor  $R_Q$  has to be in a dimension to match the applied  $V_S$  to keep  $I_Q$  limited to the operating range of maximum 25 mA.

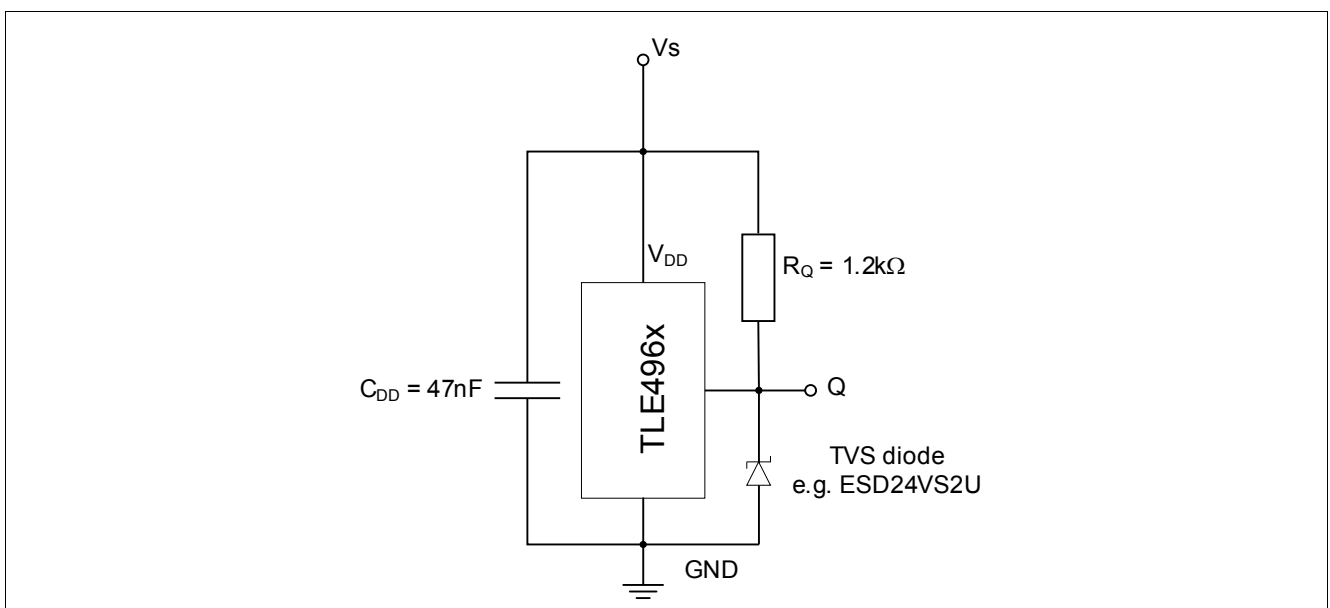
e.g.:

$$V_S = 12\text{ V}$$

$$I_Q = 12\text{ V}/1200\ \Omega = 10\text{ mA}$$



**Figure 3-1 Application Circuit 1: With External Resistor**



**Figure 3-2 Application Circuit 2: Without External Resistor**

### 3.2 Absolute Maximum Ratings

**Table 3-1 Absolute Maximum Rating Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Supply voltage <sup>1)</sup>	V <sub>DD</sub>	-18		32 42	V	10h, no external resistor required
Output voltage	V <sub>Q</sub>	-0.5		32	V	
Reverse output current	I <sub>Q</sub>	-70			mA	
Junction temperature <sup>1)</sup>	T <sub>J</sub>	-40		155 165 175 195	°C	for 2000h (not additive) for 1000h (not additive) for 168h (not additive) for 3 x 1h (additive)
Storage temperature	T <sub>S</sub>	-40		150	°C	
Thermal resistance Junction ambient	R <sub>thJA</sub>			200	K/W	for PG-SSO-3-2 (2s2p)
Thermal resistance Junction lead	R <sub>thJL</sub>			150	K/W	for PG-SSO-3-2

1) This lifetime statement is an anticipation based on an extrapolation of Infineon's qualification test results. The actual lifetime of a component depends on its form of application and type of use etc. and may deviate from such statement. The lifetime statement shall in no event extend the agreed warranty period.

**Attention: Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the integrated circuit.**

Calculation of the dissipated power P<sub>DIS</sub> and junction temperature T<sub>J</sub> of the chip (SSO3 example):

e.g for: V<sub>DD</sub> = 12 V, I<sub>S</sub> = 2.5 mA, V<sub>QSAT</sub> = 0.5 V, I<sub>Q</sub> = 20 mA

Power dissipation: P<sub>DIS</sub> = 12 V x 2.5 mA + 0.5 V x 20 mA = 30 mW + 10 mW = 40 mW

Temperature ΔT = R<sub>thJA</sub> x P<sub>DIS</sub> = 200 K/W x 40 mW = 8 K

For T<sub>A</sub> = 150 °C: T<sub>J</sub> = T<sub>A</sub> + ΔT = 150 °C + 8 K = 158 °C

**Table 3-2 ESD Protection<sup>1)</sup> (TA = 25°C)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
ESD voltage (HBM) <sup>2)</sup>	V <sub>ESD</sub>	-7		7	kV	R = 1.5 kΩ, C = 100 pF  with circuit shown in <a href="#">Figure 3-1</a> & <a href="#">Figure 3-2</a>
ESD voltage (SDM) <sup>3)</sup>		-1		1		
ESD voltage (system level) <sup>4)</sup>		-15		15		

1) Characterization of ESD is carried out on a sample basis, not subject to production test.

2) Human Body Model (HBM) tests according to EIA/JESD22-A114.

3) Socket device model (SDM) tests according to EOS/ESD-DS5.3-1993.

4) Gun test (2kΩ / 330pF or 330Ω / 150pF) according to ISO 10605-2008.

### 3.3 Operating Range

The following operating conditions must not be exceeded in order to ensure correct operation of the TLE4961-1L. All parameters specified in the following sections refer to these operating conditions unless otherwise mentioned.

**Table 3-3 Operating Conditions Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Supply voltage	$V_{DD}$	3.0		32 <sup>1)</sup>	V	
Output voltage	$V_Q$	-0.3		32	V	
Junction temperature	$T_j$	-40		170	°C	
Output current	$I_Q$	0		25	mA	
Magnetic signal input frequency <sup>2)</sup>	$f_{SW}$	0		10	kHz	

- 1) Latch-up test with factor 1.5 is not covered. Please see max ratings also.
- 2) For operation at the maximum switching frequency the magnetic input signal must be 1.4 times higher than for static fields. This is due to the -3dB corner frequency of the internal low-pass filter in the signal path.

### 3.4 Electrical and Magnetic Characteristics

Product characteristics involve the spread of values guaranteed within the specified voltage and ambient temperature range. Typical characteristics are the median of the production and correspond to  $V_{DD} = 12\text{ V}$  and  $T_A = 25^\circ\text{C}$ . The below listed specification is valid in combination with the application circuit shown in [Figure 3-1](#) and [Figure 3-2](#)

**Table 3-4 General Electrical Characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Supply current	$I_S$	1.1	1.6	2.5	mA	
Reverse current	$I_{SR}$		0.05	1	mA	for $V_{DD} = -18\text{ V}$
Output saturation voltage	$V_{QSAT}$		0.2	0.5	V	$I_Q = 20\text{ mA}$
			0.24	0.6	V	$I_Q = 25\text{ mA}$
Output leakage current	$I_{QLEAK}$			10	$\mu\text{A}$	
Output current limitation	$I_{QLIMIT}$	30	56	70	mA	internally limited & thermal shutdown
Output fall time <sup>1)</sup>	$t_f$	0.17	0.4	1	$\mu\text{s}$	1.2 k $\Omega$ / 50 pF, see <a href="#">Figure 2-3</a>
Output rise time <sup>1)</sup>	$t_r$	0.4	0.5	1	$\mu\text{s}$	1.2 k $\Omega$ / 50 pF, see <a href="#">Figure 2-3</a>
Output jitter <sup>1)2)</sup>	$t_{QJ}$		0.35	1	$\mu\text{s}$	For square wave signal with 1 kHz
Delay time <sup>1)3)</sup>	$t_d$	12	15	30	$\mu\text{s}$	see <a href="#">Figure 2-3</a>
Power-on time <sup>1)4)</sup>	$t_{PON}$		80	150	$\mu\text{s}$	$V_{DD} = 3\text{ V}$ , $B \leq B_{RP} - 0.5\text{ mT}$ or $B \geq B_{OP} + 0.5\text{ mT}$
Chopper frequency <sup>1)</sup>	$f_{OSC}$		350		kHz	

- 1) Not subject to production test, verified by design/characterization.
- 2) Output jitter is the  $1\sigma$  value of the output switching distribution.
- 3) Systematic delay between magnetic threshold reached and output switching.
- 4) Time from applying  $V_{DD} = 3.0\text{ V}$  to the sensor until the output is valid.

**Table 3-5 Magnetic Characteristics**

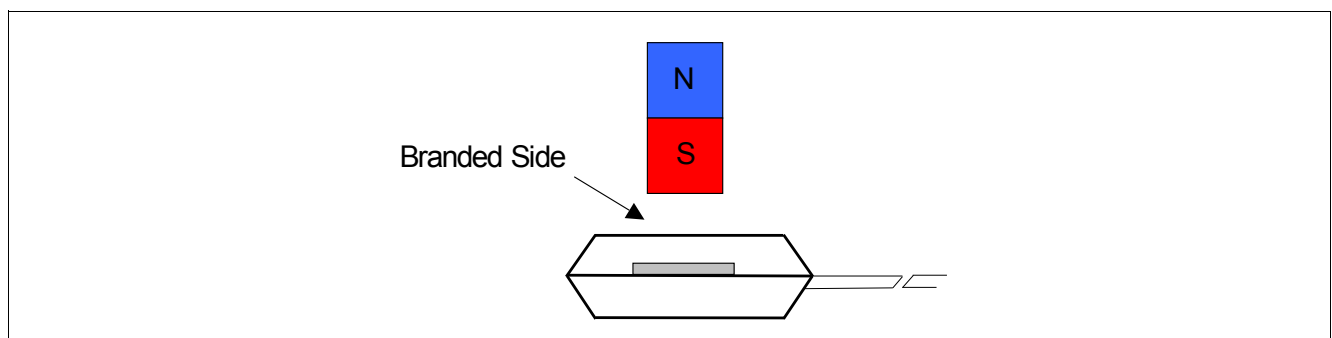
Parameter	Symbol	T (°C)	Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
Operating point	B <sub>OP</sub>	-40	0.6	2.1	3.6	mT	
		25	0.5	2.0	3.5		
		170	0.2	1.6	3.1		
Release point	B <sub>RP</sub>	-40	-3.6	-2.1	-0.6	mT	
		25	-3.5	-2.0	-0.5		
		170	-3.1	-1.6	-0.2		
Hysteresis	B <sub>HYS</sub>	-40	2.7	4.2	5.7	mT	
		25	2.6	4.0	5.4		
		170	2.0	3.2	4.4		
Effective noise value of the magnetic switching points <sup>1)</sup>	B <sub>Neff</sub>	25		62		μT	
Temperature compensation of magnetic thresholds <sup>2)</sup>	T <sub>C</sub>			-1200		ppm/K	

1) The magnetic noise is normal distributed and can be assumed as nearly independent to frequency without sampling noise or digital noise effects. The typical value represents the rms-value and corresponds therefore to a 1  $\sigma$  probability of normal distribution. Consequently a 3  $\sigma$  value corresponds to 99.7% probability of appearance.

2) Not subject to production test, verified by design/characterization.

**Field Direction Definition**

Positive magnetic fields are defined with the south pole of the magnet to the branded side of package.



**Figure 3-3 Definition of Magnetic Field Direction PG-SSO-3-2**



### 3.5 Electro Magnetic Compatibility

Characterization of Electro Magnetic Compatibility is carried out on a sample basis from one qualification lot. Not all specification parameters have been monitored during EMC exposure.

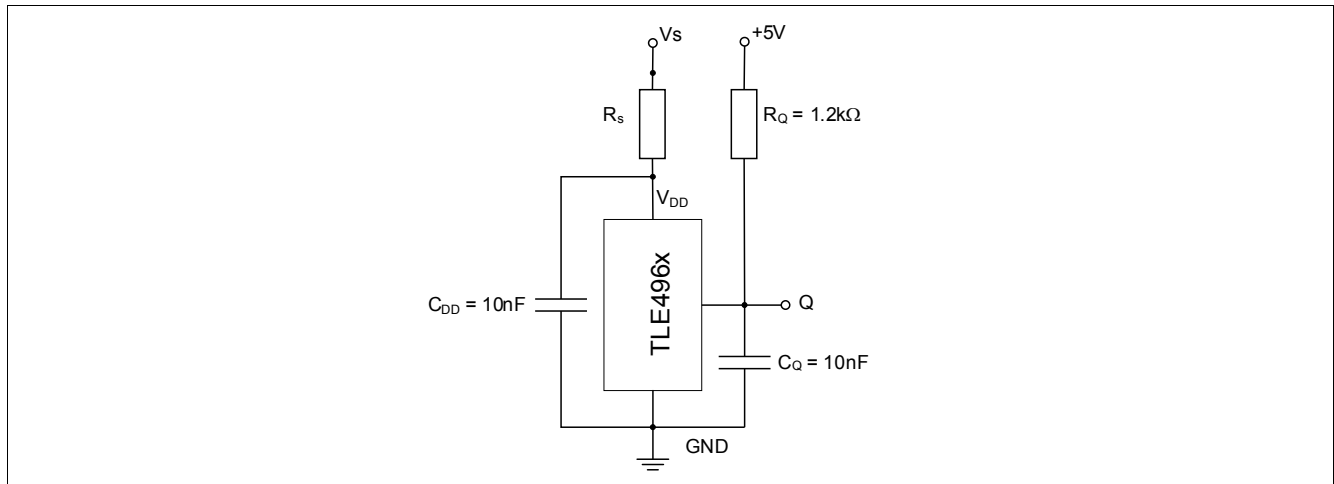


Figure 3-4 EMC Test Circuit

Ref: ISO 7637-2 (Version 2004), test circuit [Figure 3.4](#) (with external resistor,  $R_S = 100 \Omega$ )

Table 3-6 Magnetic Compatibility

Parameter	Symbol	Level / Type	Status
Testpulse 1	$V_{EMC}$	-100 V	C
Testpulse 2a <sup>1)</sup>		60 V/110 V	A/C
Testpulse 2b		10 V	C
Testpulse 3a		-150 V	A
Testpulse 3b		100 V	A
Testpulse 4 <sup>2)</sup>		-7 V / -5.5 V	A
Testpulse 5b <sup>3)</sup>		$U_S = 86.5 \text{ V} / U_S^* = 28.5 \text{ V}$	A

1) ISO 7637-2 (2004) describes internal resistance = 2  $\Omega$  (former 10  $\Omega$ ).

2) According to 7637-2 for test pulse 4 the test voltage shall be 12 V +/- 0.2 V.

3) A central load dump protection of 42 V is used.  $U_S^* = 42 \text{ V}$ -13.5 V.

Ref: ISO 7637-2 (Version 2004), test circuit [Figure 3.4](#) (without external resistor,  $R_S = 0\Omega$ )

Table 3-7 Electro Magnetic Compatibility

Parameter	Symbol	Level / Type	Status
Testpulse 1	$V_{EMC}$	-50 V	C
Testpulse 2a <sup>1)</sup>		50 V	A
Testpulse 2b		10 V	C
Testpulse 3a		-150 V	A
Testpulse 3b		100 V	A
Testpulse 4 <sup>2)</sup>		-7 V / 5.5 V	A
Testpulse 5b <sup>3)</sup>		$U_S = 86.5 \text{ V} / U_S^* = 28.5 \text{ V}$	A

1) ISO 7637-2 (2004) describes internal resistance = 2  $\Omega$  (former 10  $\Omega$ ).

2) According to 7637-2 for test pulse 4 the test voltage shall be 12 V +/- 0.2 V.

3) A central load dump protection of 42 V is used.  $U_S^* = 42 \text{ V}$ -13.5 V.

## 4 Package Information

The TLE4961-1L is available in the through-hole leaded package PG-SSO-3-2.

### 4.1 Package Outline PG-SSO-3-2

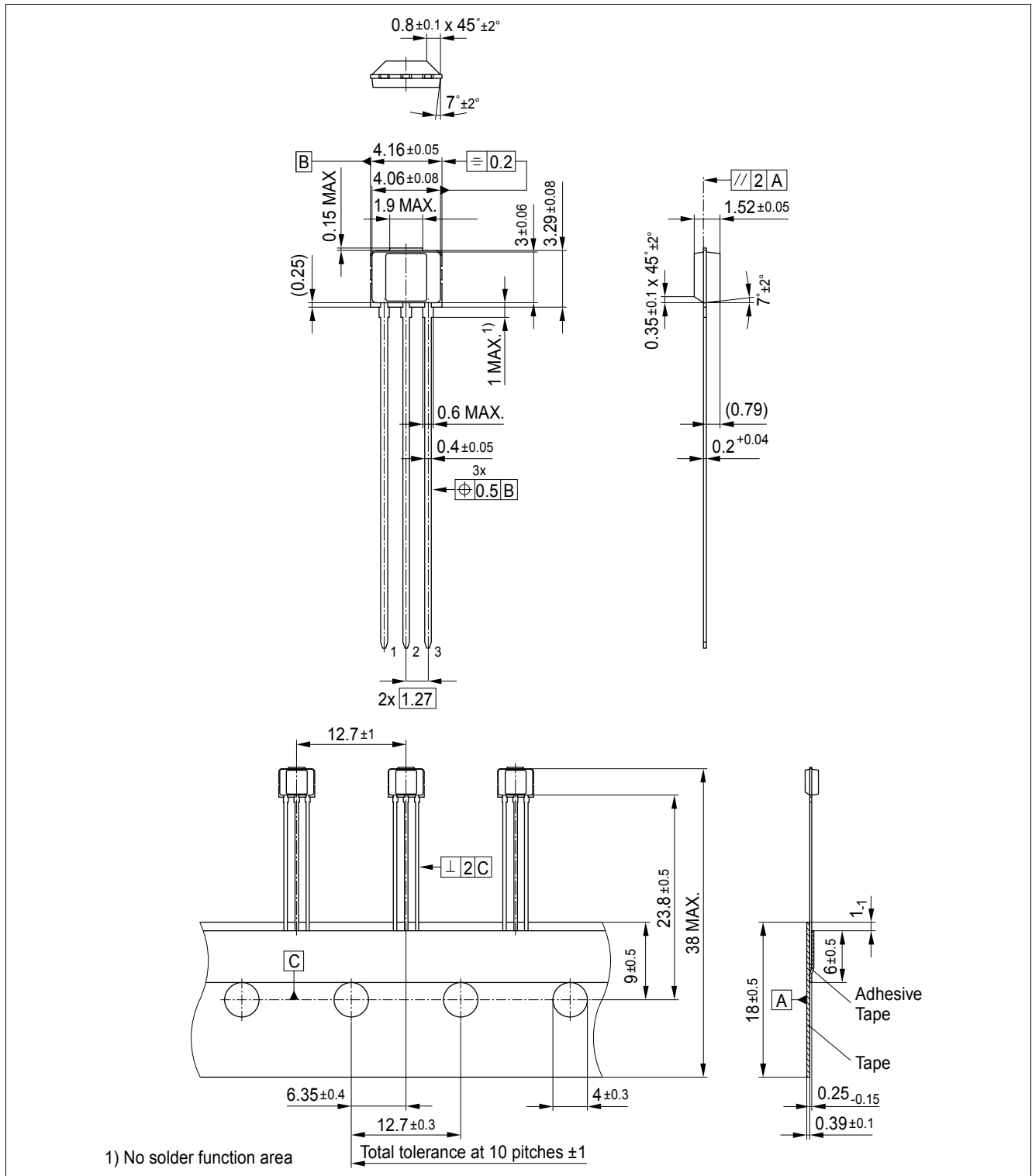


Figure 4-1 PG-SSO-3-2 Package Outline (All Dimensions in mm)

### 4.2 PG-SSO-3-2 Distance between Chip and Package

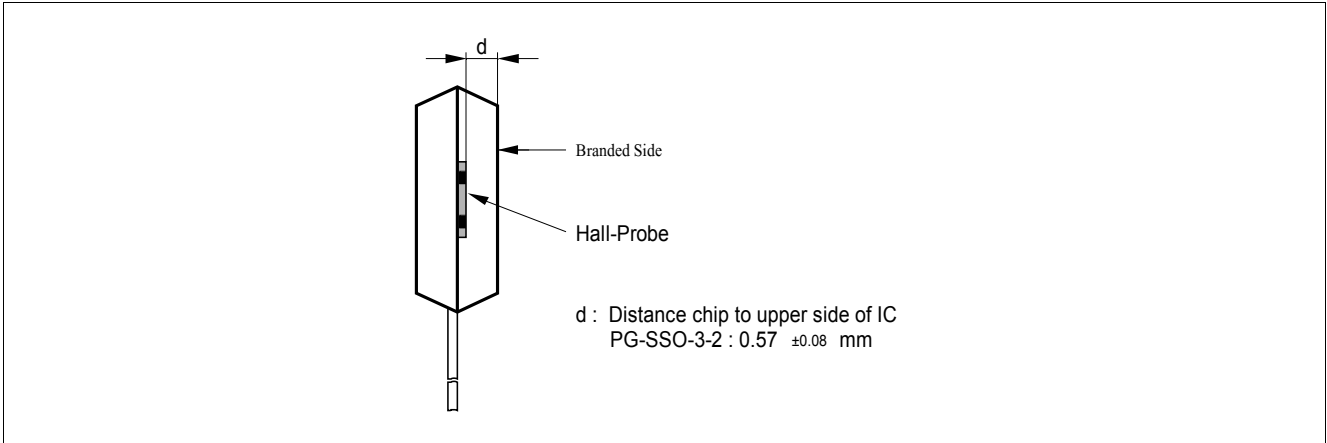


Figure 4-2 Distance between Chip and Package

### 4.3 Package Marking

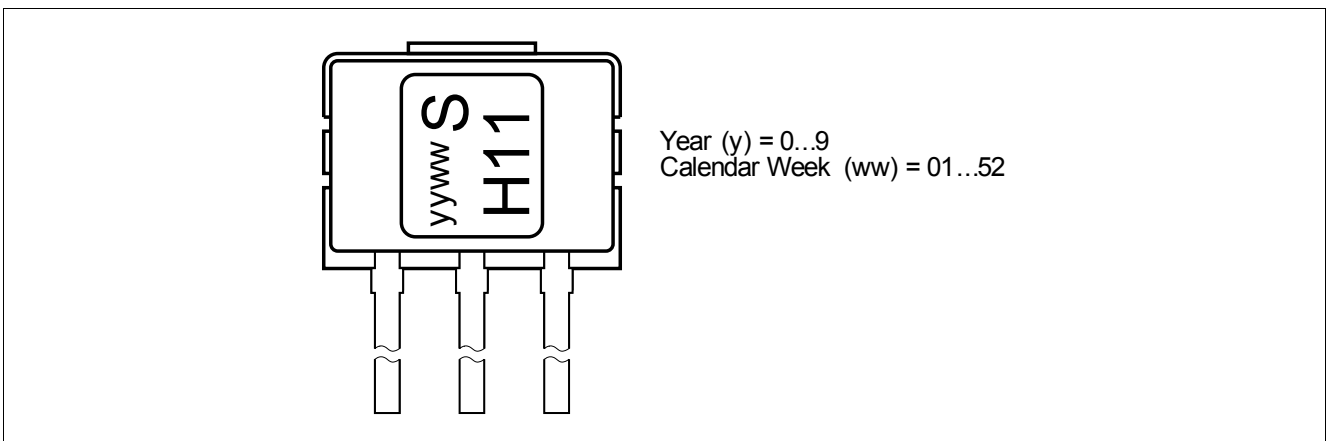


Figure 4-3 Marking of TLE4961-1L

## 5 Graphs of the Magnetic Parameters

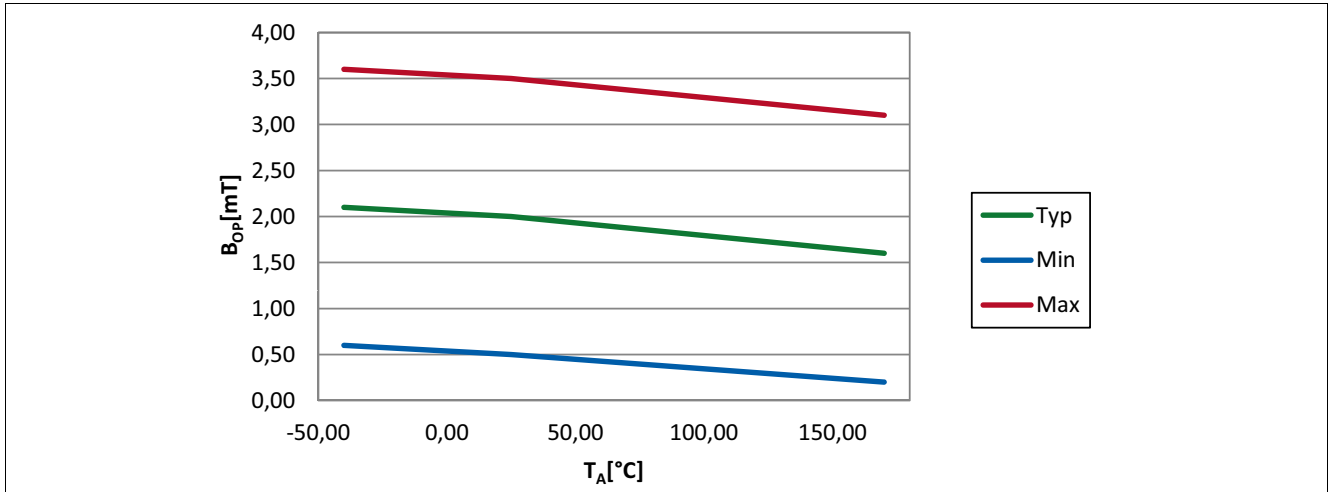


Figure 5-1 Operating Point ( $B_{OP}$ ) of the TLE4961-1L over Temperature

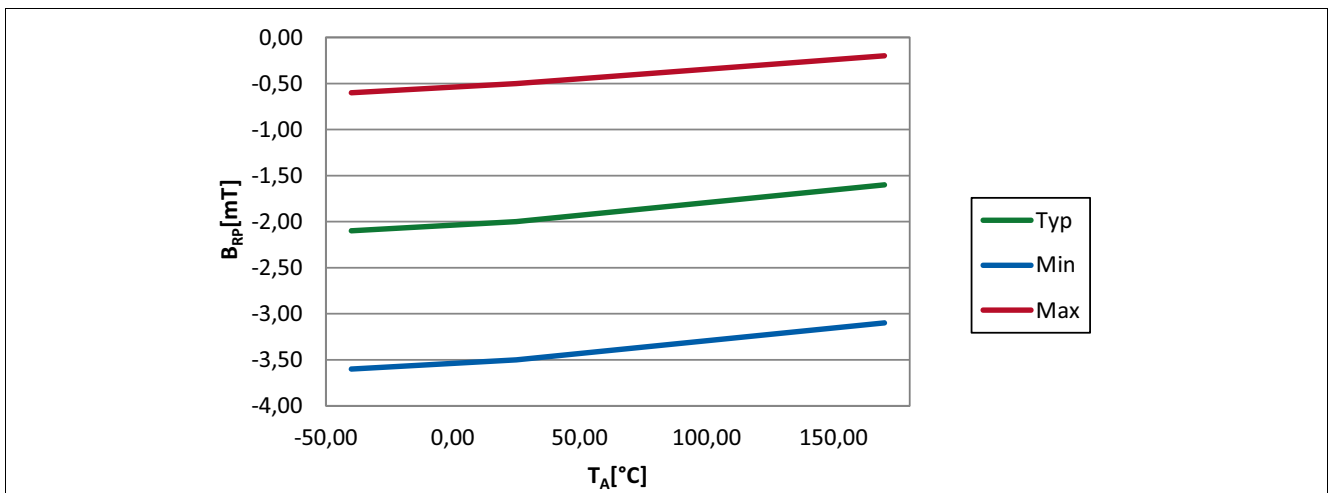


Figure 5-2 Release Point ( $B_{RP}$ ) of the TLE4961-1L over Temperature

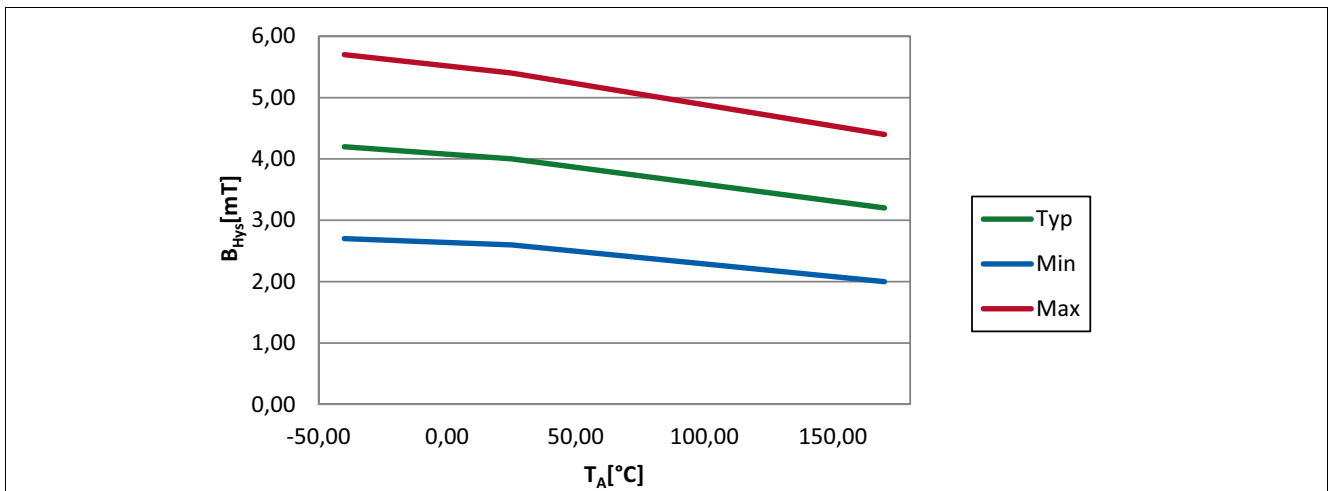


Figure 5-3 Hysteresis ( $B_{Hys}$ ) of the TLE4961-1L over Temperature



## 6 Graphs of the Electrical Parameters

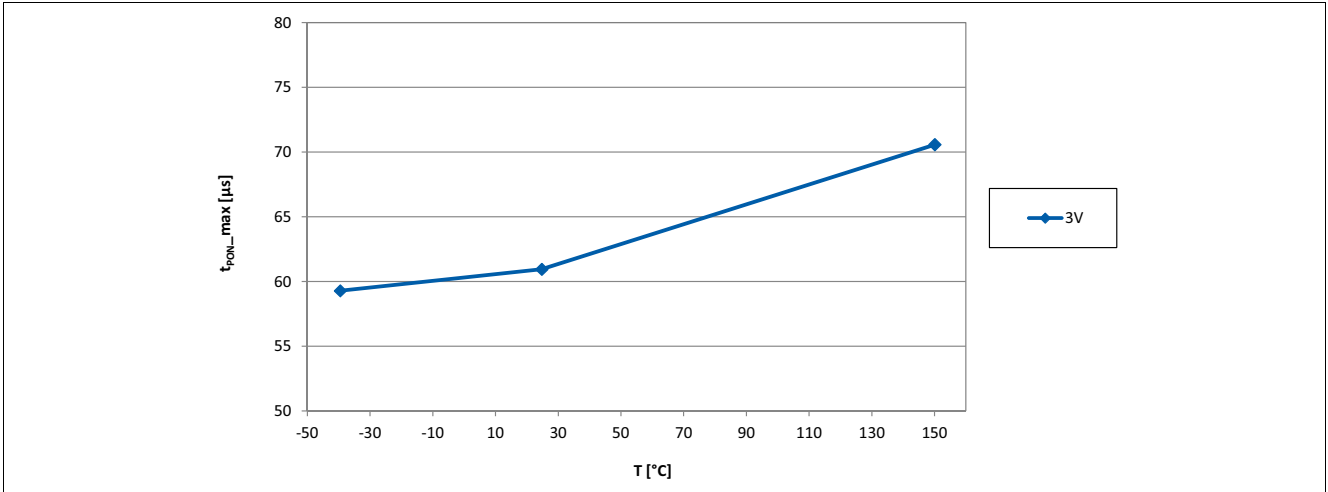


Figure 6-1 Power On Time  $t_{PON}$  of the TLE4961-1L over Temperature

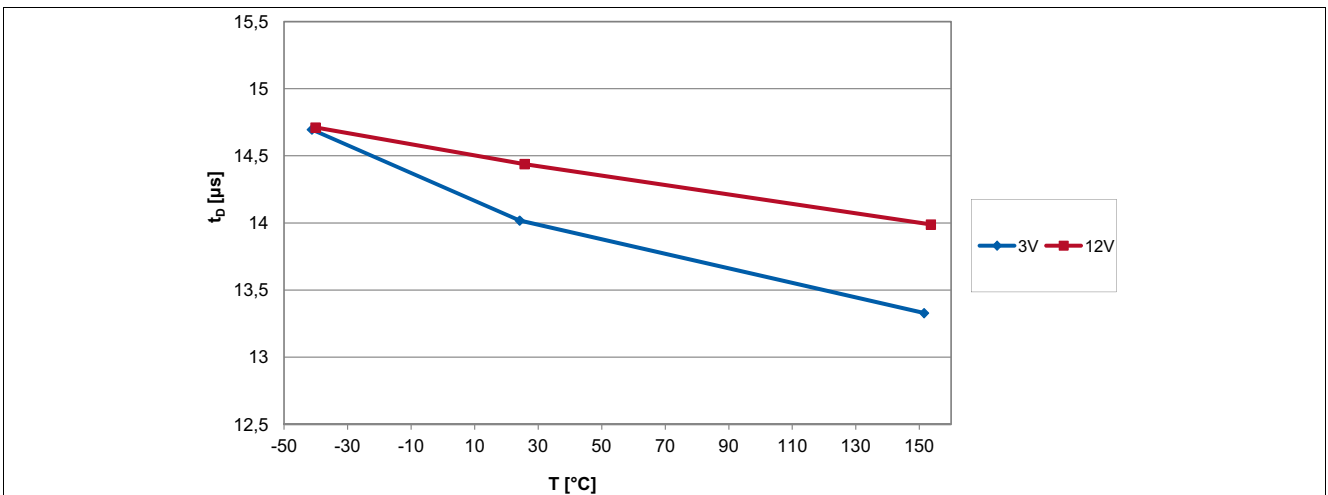


Figure 6-2 Signal Delay Time of the TLE4961-1L over Temperature

Graphs of the Electrical Parameters

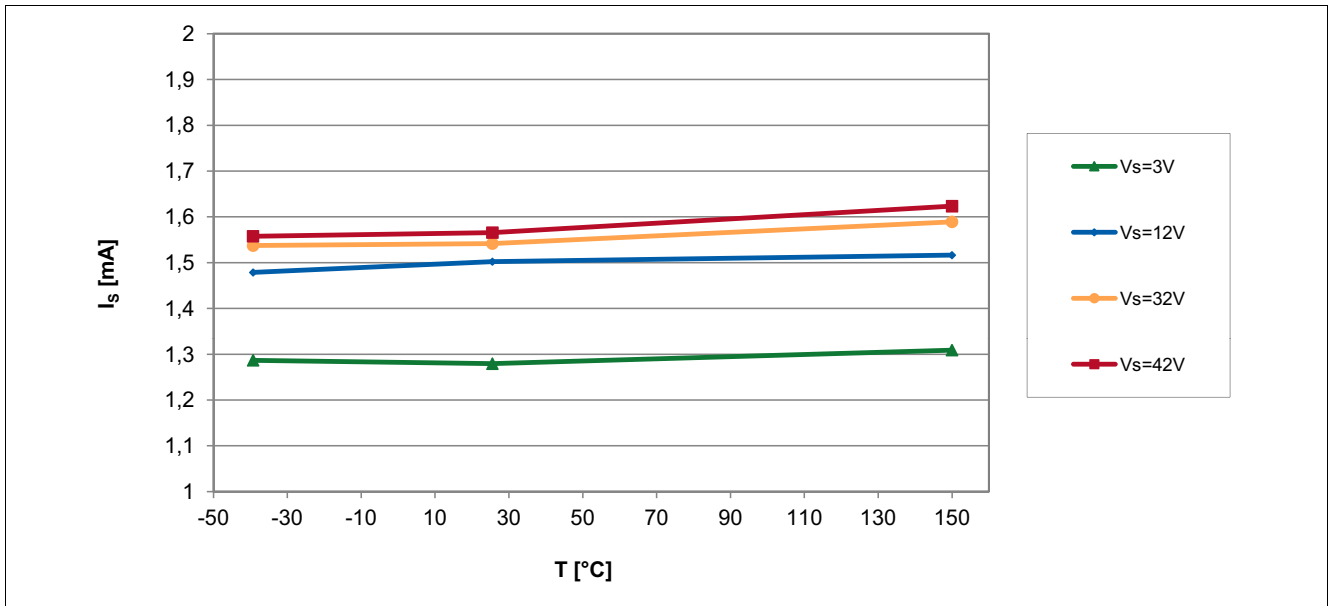


Figure 6-3 Supply Current of the TLE4961-1L over Temperature

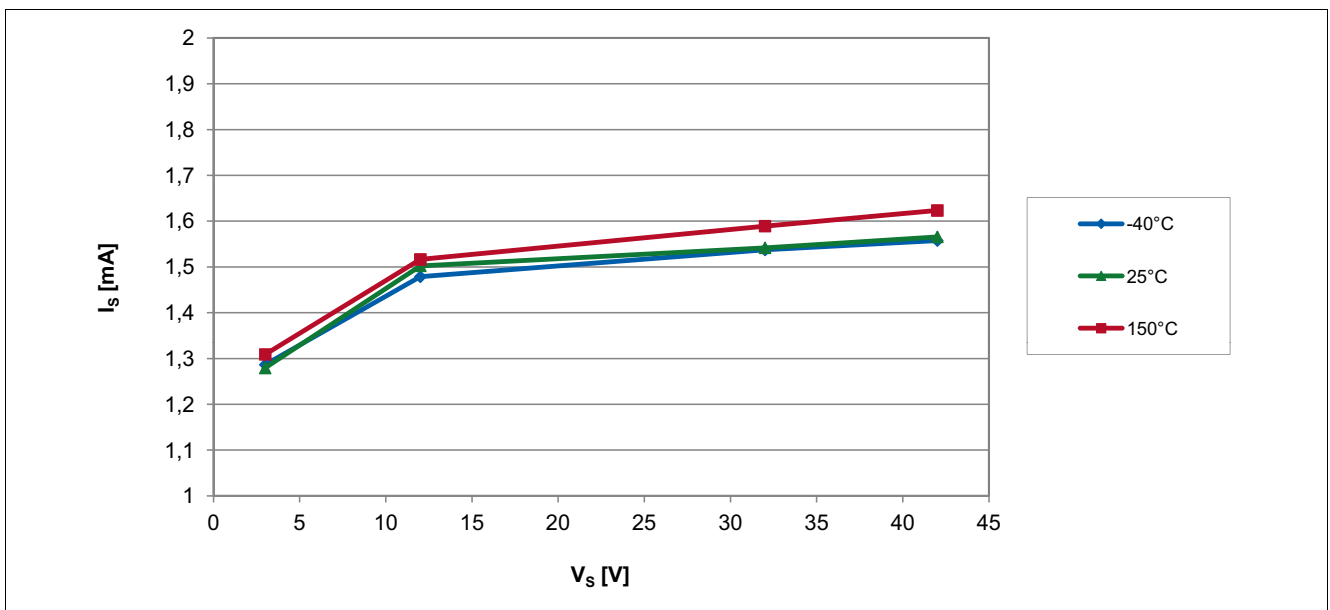


Figure 6-4 Supply Current of the TLE4961-1L over Supply Voltage

Graphs of the Electrical Parameters

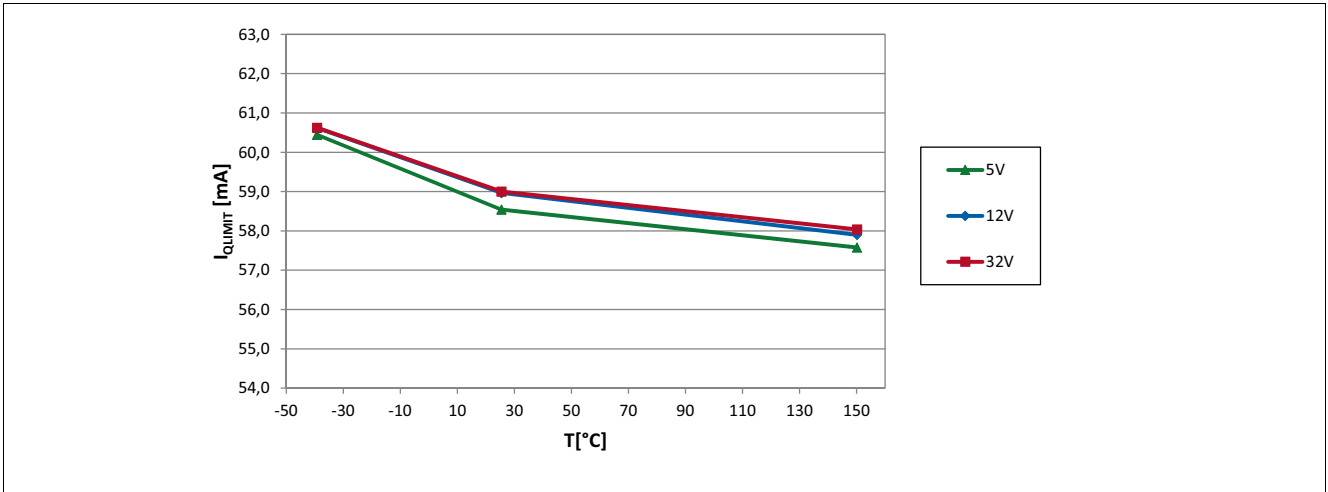


Figure 6-5 Output Current Limit of the TLE4961-1L over Temperature

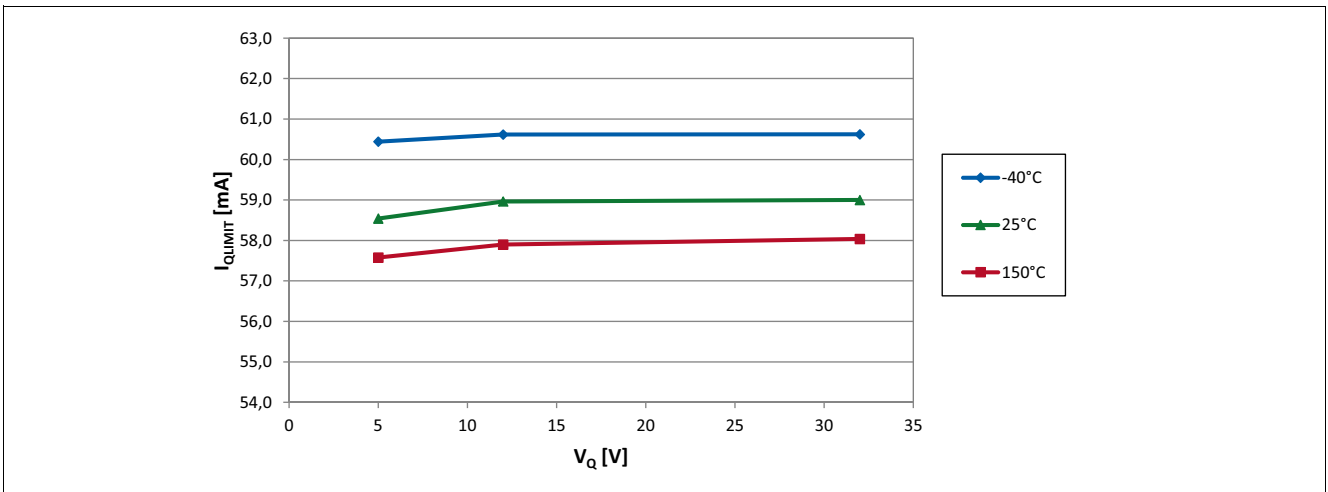


Figure 6-6 Output Current Limit of the TLE4961-1L over applied Pull-up Voltage

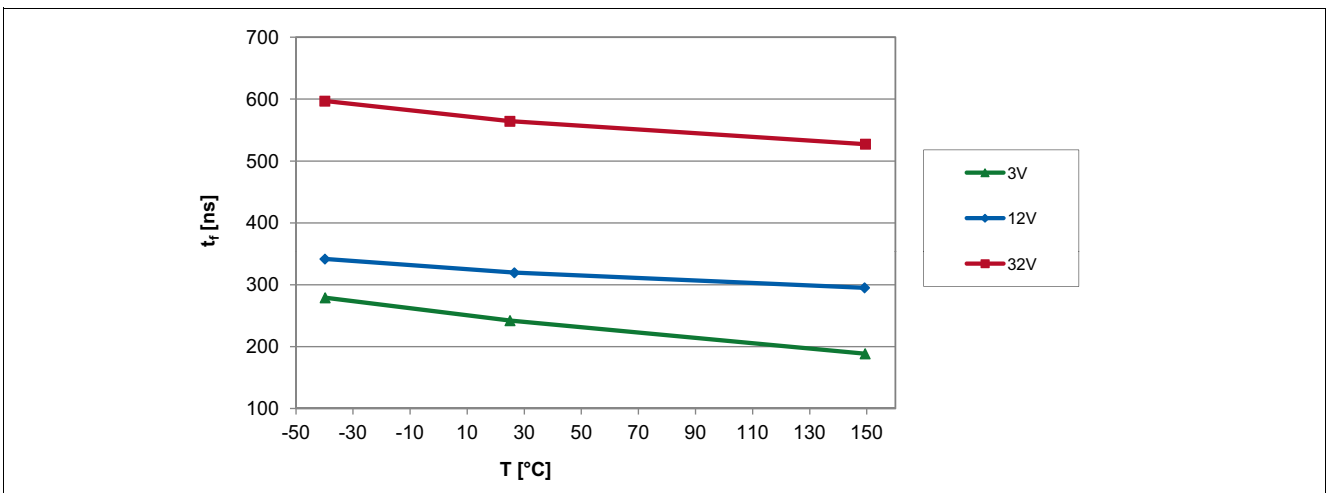


Figure 6-7 Output Fall Time of the TLE4961-1L over Temperature

Graphs of the Electrical Parameters

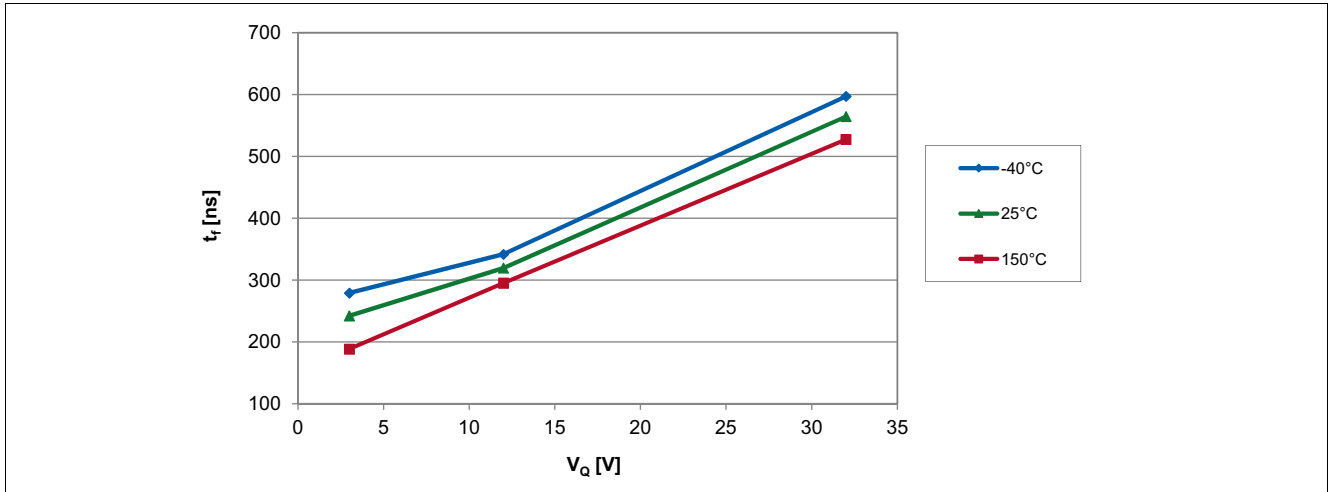


Figure 6-8 Output Fall Time of the TLE4961-1L over applied Pull-up Voltage

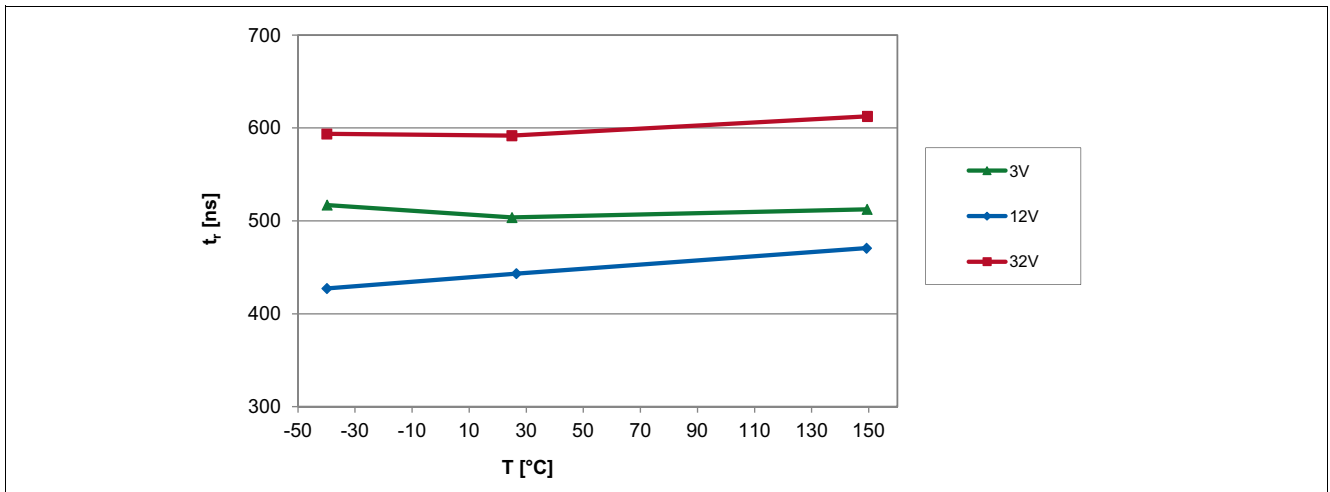


Figure 6-9 Output Rise Time of the TLE4961-1L over Temperature

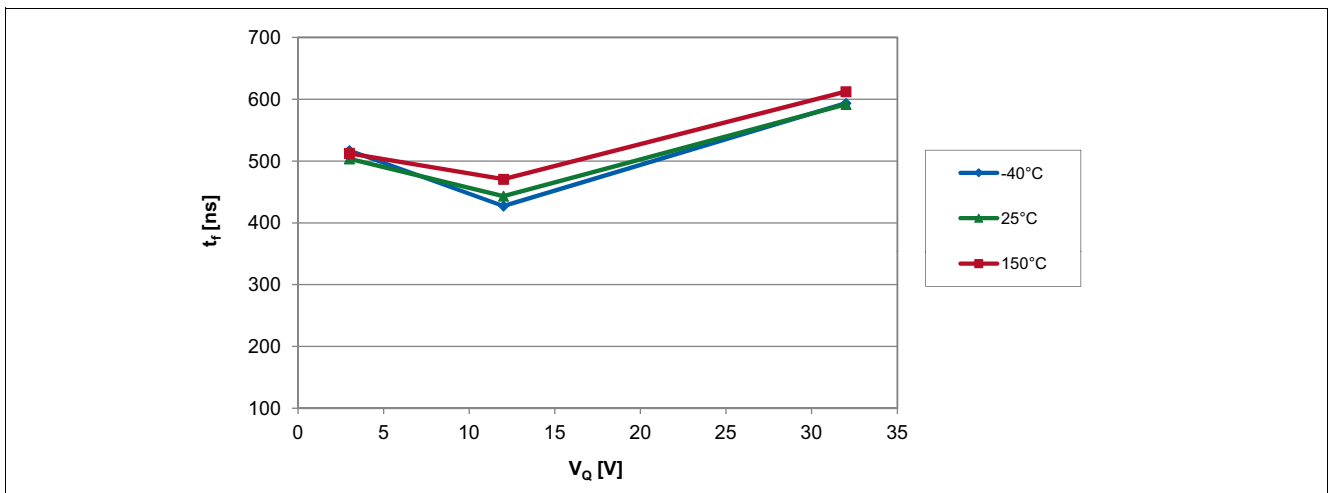


Figure 6-10 Output Rise Time of the TLE4961-1L over applied Pull-up Voltage

Graphs of the Electrical Parameters

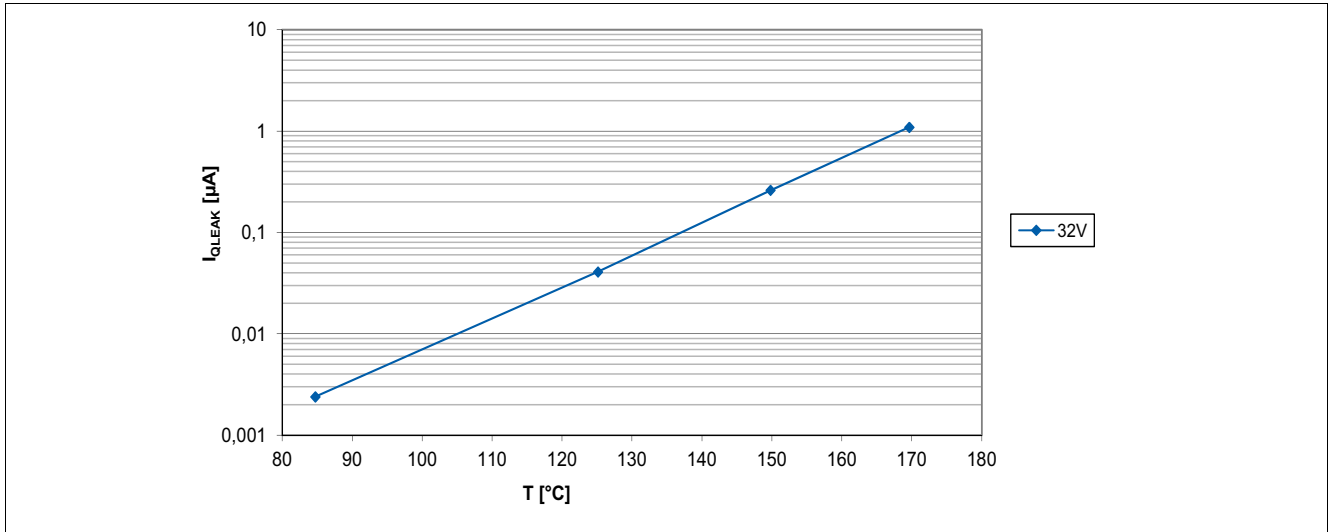


Figure 6-11 Output Leakage Current of the TLE4961-1L over Temperature

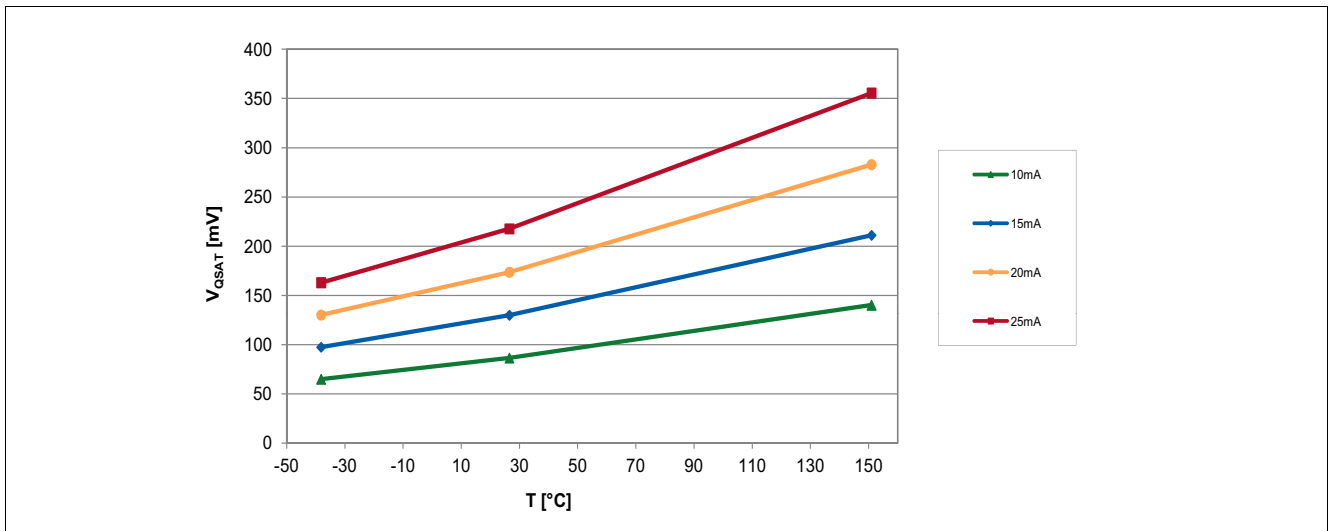


Figure 6-12 Saturation Voltage of the TLE4961-1L over Temperature

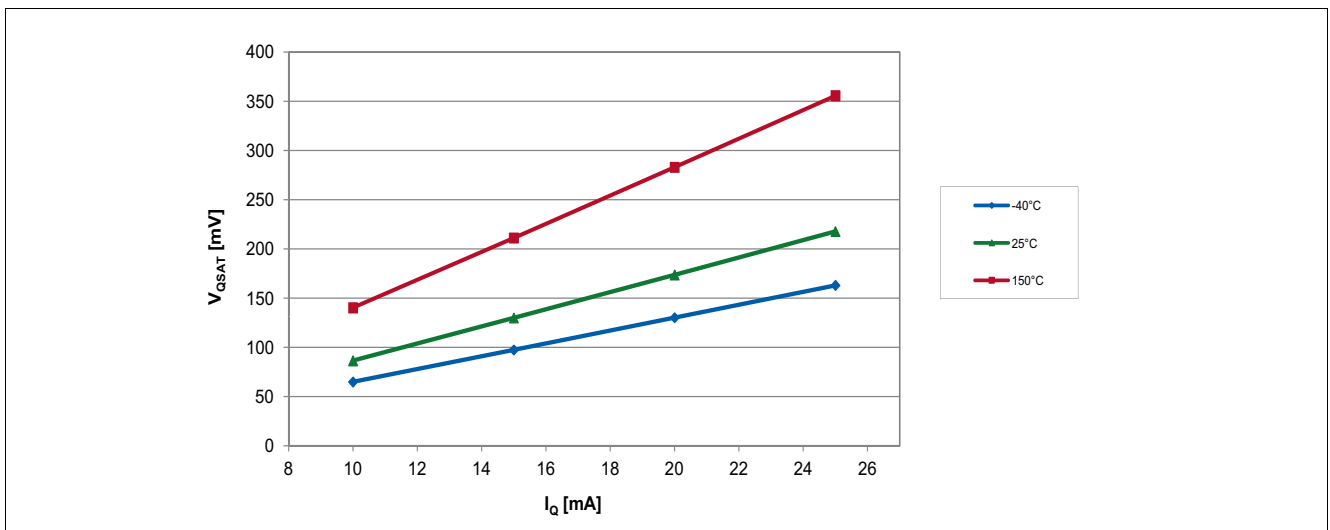


Figure 6-13 Saturation Voltage of the TLE4961-1L over Output Current

Graphs of the Electrical Parameters

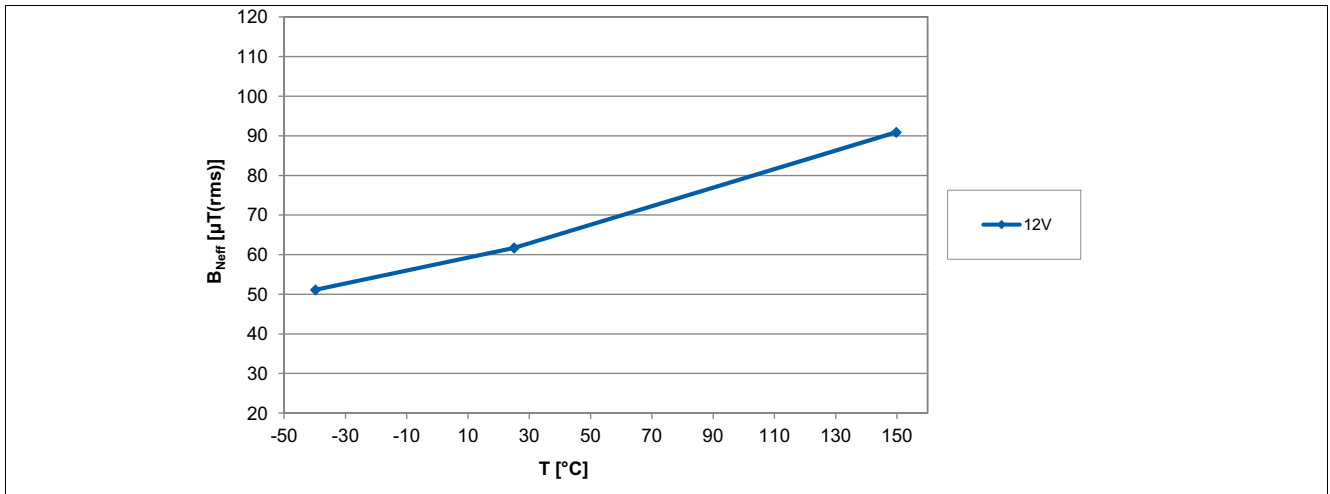


Figure 6-14 Effective Noise of the TLE4961-1L Thresholds over Temperature

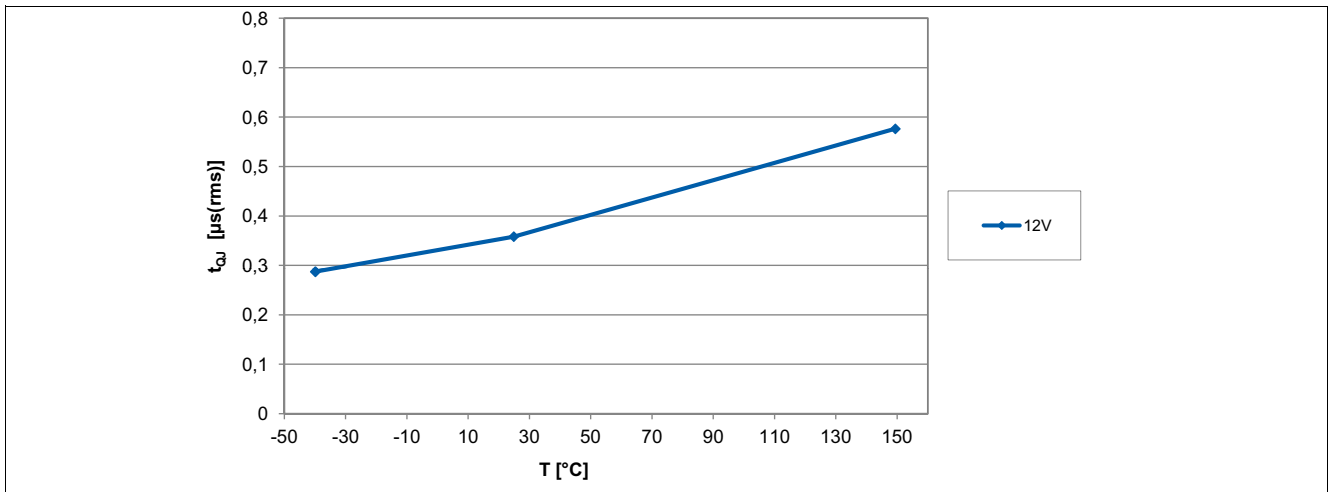


Figure 6-15 Output Signal Jitter of the TLE4961-1L over Temperature